

Edition 3.0 2008-05

INTERNATIONAL STANDARD

AMENDMENT 1

Miniature fuses -

Part 4: Universal modular fuse-links (UMF) – Through-hole and surface mount types

Document Preview

IEC 60127-4:2005/AMD1:2008

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRICE CODE



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FOREWORD

This amendment has been prepared by subcommittee 32C: Miniature fuses, of IEC technical committee 32: Fuses.

The text of this amendment is based on the following documents:

FDIS	Report on voting
32C/411/FDIS	32C/412/RVD

Full information on the voting for the approval of this amendment can be found in the report on voting indicated in the above table.

The committee has decided that the contents of this amendment and the base publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- · reconfirmed,
- withdrawn.
- · replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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7.3 Fuse-bases for tests

7.3.1 General requirements

Replace, in the second paragraph, the second dashed item commencing "... the nominal thickness of copper layer ... " by the following:

- the nominal thickness of copper layer shall be 0,035 mm (0.070 mm for rated currents above 5 A).

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8.6 Solderability of terminations

Add, after the title, the following new sentence:

For the tests described in 8.6.1 to 8.6.2, lead-free solder as described in Table 2 of IEC 60068-2-58 shall be used in the solder bath.

8.6.1 Through-hole fuse-links

In the list of test conditions, replace the second condition (immersion conditions) as follows:

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Immersion conditions: $250 \, ^{\circ}\text{C} \pm 3 \, ^{\circ}\text{C}, \, 3 \, \text{s} \pm 0.3 \, \text{s}$

8.6.2 Surface mount fuse-links

Replace the first sentence as follows:

The fuse-links shall be tested according to 6.2 of IEC 60068-2-58, with the following conditions:

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In the list of test conditions, replace the second condition (immersion conditions) as follows:

Immersion conditions: 250 °C \pm 3 °C, 3 s \pm 0,3 s

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8.7.2 Surface mount fuse-links

Replace the first sentence as follows:

The fuse-links shall be tested according to 6.2 of IEC 60068-2-58, with the following conditions:

9.7 Fuse-link temperature

Preview

In item a) replace the second sentence "The temperature rise shall not exceed 70 K for rated current up to and including 6,3 A, and 85 K for rated current above 6,3 A;" by the following:

The temperature rise shall not exceed 75 K for fuse-links with rated current up to and including 6,3 A and 95 K for rated current above 6,3 A;

In item b) replace the last sentence "The temperature rise shall not exceed 85 K." by the following:

The temperature rise shall not exceed 95 K.

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Figure 2 - Test board for through-hole fuse-links

Replace, in the key to Figure 2, all three occurrences of "6,3 A" by "5 A".

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Figure 3 - Test board for surface mount fuse-links

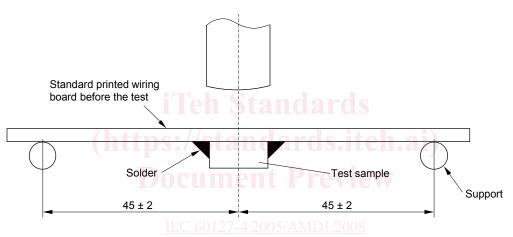
Replace, in the key to Figure 3, the two references to "6,3 A" by "5 A".

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Figure 5– Bending jig for surface-mount fuse-links

Replace the drawings of Figure 5 by the following new drawings:

Dimensions in millimetres



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